L Number	Hits	Search Text	DB	Time stamp
1	2	("6313532").PN.	USPAT; US-PGPUB;	2003/07/31 15:05
2	73	inoue-kosuke.in.	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/31 15:16
3	11	tenmei-hiroyuki.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:18
4	86	yamaguchi-yoshihide.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/31 15:20
6	36	hozoji-hiroshi.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:21
7	118	Tsunoda-shigeharu.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/31 15:21
8	22	minagawa-madoka.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:22
9	36	kanda-naoya.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:22
13	31	ujiie-kenji.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:24
12	51	yajima-akira.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:25
11	397	nishimura-asao.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:26
5	13	oroku-noriyuki.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:32
10	159	anjo-ichiro.in.	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/31 15:34

14 13 257/777-783.ccls. and insulat\$4 and USPAT; protrus\$4 and inclin\$4 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; and protrus\$4 and inclin\$4 USPAT; US-PGPUB;	2003/07/31 15:36
EPO; JPO; DERWENT; IBM_TDB USPAT;	15.50
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IBM_TDB 15 12 257/787,792-793,784.ccls. and insulat\$4 USPAT;	
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and protrus\$4 and inclin\$4 US-PGPUB; EPO; JPO;	15.50
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20 5870 (insulat\$4 dielectric) with inclin\$4 USPAT; US-PGPUB;	15:44
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83 (insulat\$4 dielectric) with inclin\$4 and USPAT; (bump ball) and (IC chip die) US-PGPUB;	15:58
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22 33 257/734,759,773.ccls. and (insulat\$4 USPAT;	2003/07/31
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24 532 (insulat\$4 dielectric) with protrus\$4 and USPAT;	2003/07/31
inclin\$4 US-PGPUB;	16:48
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25 633 257/\$.ccls. and (insulat\$4 dielectric) USPAT;	2003/07/31
with protrus\$4 and semiconductor US-PGPUB;	16:50
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26 12 ("4025411" "4073054" "4180432" USPAT	2003/07/31
"4451326" "4466177" "4470874"	17:02
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